

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

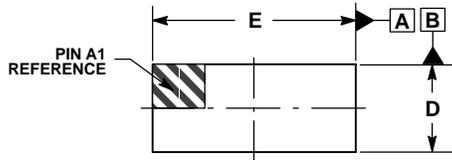
ON Semiconductor®



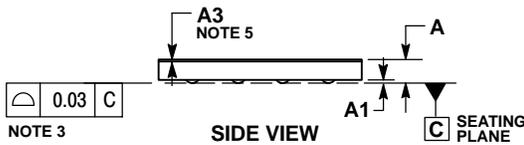
SCALE 4:1

WLCSP8, 0.97x2.25X0.265
CASE 567TE
ISSUE A

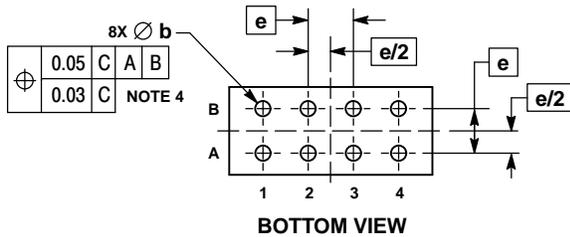
DATE 10 MAR 2017



TOP VIEW

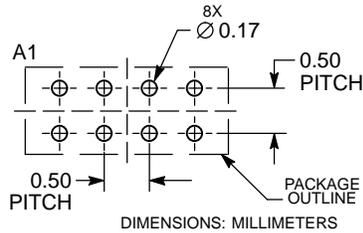


SIDE VIEW



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DIMENSION b IS MEASURED AT THE MAXIMUM BALL DIAMETER PARALLEL TO DATUM C.
5. DIMENSION A3 IS AN OPTIONAL BACKSIDE COATING LAYER.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.24	0.265	0.29
A1	0.04 REF		
A3	0.025 REF		
b	0.12	0.17	0.22
D	0.92	0.97	1.02
E	2.20	2.25	2.30
e	0.50 BSC		

GENERIC MARKING DIAGRAM*



- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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NEW STANDARD:		
DESCRIPTION:	WLCSP8, 0.97X2.25X0.265	PAGE 1 OF 2

